

MOS FET FK3503010L

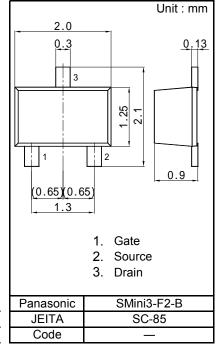
FK3503010L Silicon N-channel MOSFET

For switching FK330301 in SMini3 type package

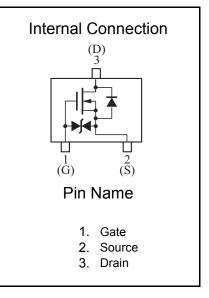
Features

- Low drive voltage : 2.5 V drive
- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol : X1
- Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C						
Parameter	Symbol	Rating	Unit			
Drain-source voltage	VDS	30	V			
Gate-source voltage	VGS	±12	V			
Drain current	ID	100	mA			
Pulse drain current	IDp	200	mA			
Total power dissipation	PD	150	mW			
Channel temperature	Tch	150	°C			
Operating ambient temperature	Topr	-40 to + 85	°C			
Storage temperature	Tstg	-55 to +150	°C			



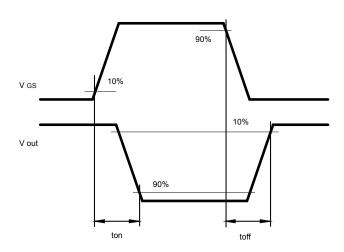


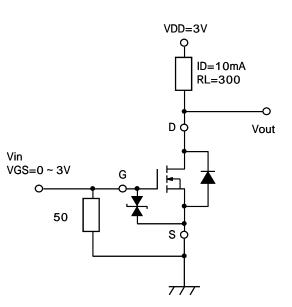
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■ Electrical Characteristics Ta = 25 °C ± 3 °C							
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Drain-source breakdown voltage	VDSS	ID = 1 mA, VGS = 0	30			V	
Drain-source cutoff current	IDSS	VDS = 30 V, VGS = 0			1.0	μA	
Gate-source cutoff current	IGSS	VGS = ±10 V, VDS = 0			±10	μA	
Gate threshold voltage	VTH	ID = 1.0 μA, VDS = 3.0 V	0.5	1.0	1.5	V	
Drain-source ON resistance	RDS(on)	ID = 10 mA, VGS = 2.5 V		3	6	Ω	
		ID = 10 mA, VGS = 4.0 V		2	3	Ω	
Forward transfer admittance	Yfs	ID = 10 mA, VDS = 3.0 V	20	55		mS	
Input capacitance	Ciss			12		pF	
Output capacitance	Coss	VDS = 3 V, VGS = 0, f = 1 MHz		7		pF	
Reverse transfer capacitance	Crss			3		pF	
Turn-on time ^{*1}	ton	VDD = 3 V, VGS = 0 to 3 V	100			ne	
		ID = 10 mA		100		ns	
Turn-off time ^{*1}	toff	VDD = 3 V, VGS = 3 to 0 V		100		ns	
		ID = 10 mA					

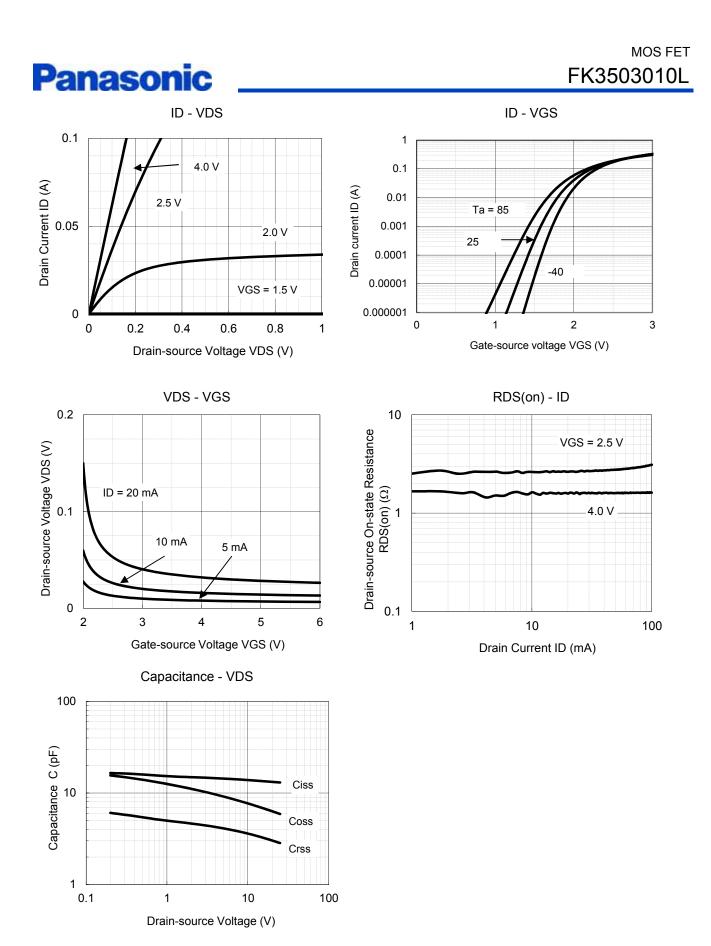
 Note)
 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

 2. *1
 Turn-on and Turn-off test circuit





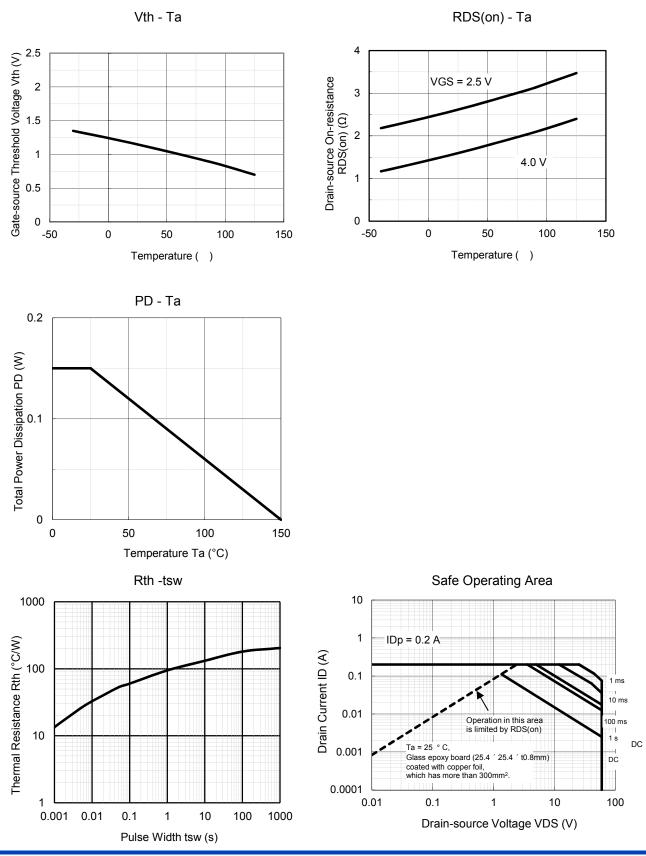






Panasonic

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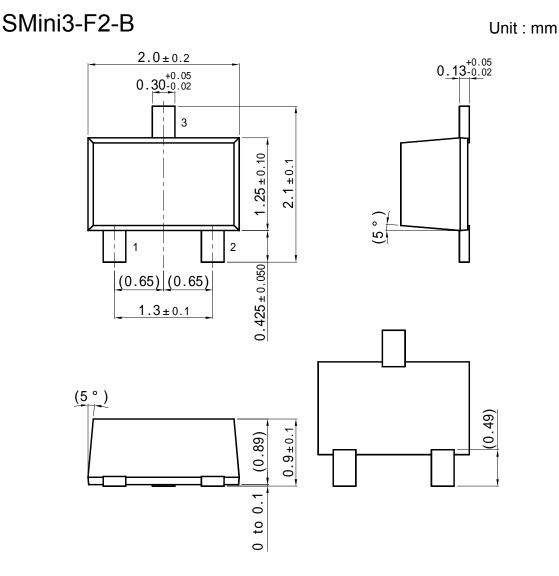


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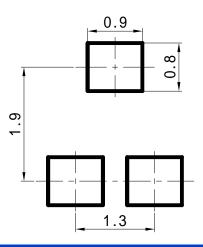
Established : 2011-05-13 Revised : 2015-05-08



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■ Land Pattern (Reference) (Unit : mm)



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